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disposed in a device hole provided in a tape carrier with one end of a lead on said tape carrier being electrically connected to an external terminal of said semiconductor chip, characterized in that said back surface of said semiconductor chip is defined by spin-etching a surface opposite to said semiconductor chip so that said semiconductor chip is less in thickness than said tape carrier, and that said semiconductor chip is sealed by a seal resin material so that said principal surface and said back surface of said semiconductor chip are covered with said seal resin material.

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5. (Amended) The semiconductor device as recited in claim 1, characterized in that a seal resin injection port for use in seal resin injection is formed at part of said tape carrier thereby causing said device hole to be coupled to a gate of a metal mold structure used during formation of said seal resin.

Remarks

This is a reply to the outstanding Office Action (first action on the merits), dated March 14, 2001, in which concurrently filed herewith is a Petition for Extension of Time covering the two-month extended time period for filing this response including the required fee amount thereof. (An authorized Credit Card Payment Form covering the fee amount for the extended time period is enclosed herewith.)